

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,700,794 B2
APPLICATION NO. : 09/915762
DATED : March 2, 2004
INVENTOR(S) : Robert S. Vinson et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 6, Line 63

Delete: "a decoupling"
Insert: -- at least one decoupling --

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Column 6, Line 63

Delete: "on each"
Insert: -- on the --

Column 7, Lines 4-5

Delete: "to a die pad and from a die pad to a substrate bonding pad"
Insert: -- to the die pads and from the die pads to the substrate bonding pads --

Column 7, Line 19

Delete: "a wire bond"
Insert: -- the wire bond --

Column 8, Line 10

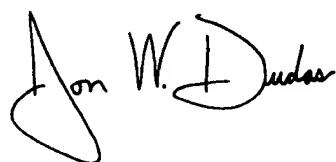
Delete: "to a logic pin and from a logic pin"
Insert: -- to the logic pin and from the logic pin --

Column 8, Line 11

Delete: "a substrate"
Insert: -- the substrate --

Signed and Sealed this

Eighteenth Day of September, 2007



JON W. DUDAS
Director of the United States Patent and Trademark Office